



SLOVENSKI STANDARD
SIST EN 60068-2-20:2009

01-januar-2009

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SIST HD 323.2.20 S3:2003

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Environmental testing -- Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads

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Umgebungseinflüsse -- Teil 2-20: Prüfungen - Prüfung T: Prüfverfahren für die Lötbarkeit und Lötwärmebeständigkeit von Bauelementen mit herausgeführten Anschlüssen

[SIST EN 60068-2-20:2009](#)

Essais d'environnement -- Partie 2-20: Essais - Essai T: Méthodes d'essai pour la brasabilité et la résistance à la chaleur de brasage des dispositifs plombés

Ta slovenski standard je istoveten z: EN 60068-2-20:2008

ICS:

19.040 Preskušanje v zvezi z Environmental testing
 okoljem

SIST EN 60068-2-20:2009 en,de

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60068-2-20

September 2008

ICS 19.040

Supersedes HD 323.2.20 S3:1988

English version

**Environmental testing -
Part 2-20: Tests -
Test T: Test methods for solderability and resistance
to soldering heat of devices with leads
(IEC 60068-2-20:2008)**

Essais d'environnement -
Partie 2-20: Essais -
Essai T: Méthodes d'essai
pour la brasabilité et la résistance
à la chaleur de brasage
des dispositifs plombés
(CEI 60068-2-20:2008)

Umgebungseinflüsse -
Teil 2-20: Prüfungen -
Prüfung T: Prüfverfahren für die Lötbarkeit
und Lötwärmebeständigkeit
von Bauelementen mit herausgeführten
Anschlüssen
(IEC 60068-2-20:2008)

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This European Standard was approved by CENELEC on 2008-08-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 91/764/FDIS, future edition 5 of IEC 60068-2-20, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60068-2-20 on 2008-08-01.

This European Standard supersedes HD 323.2.20 S3:1988.

The major technical changes with regard to HD 323.2.20 S3:1988 are the following:

- the solder globule test is deleted;
- test conditions and requirements for lead-free solders are added.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2009-05-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2011-08-01

Annex ZA has been added by CENELEC.

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Endorsement notice

The text of the International Standard IEC 60068-2-20:2008 was approved by CENELEC as a European Standard without any modification. [SIST EN 60068-2-20:2009](https://standards.iteh.ai/catalog/standards/sist/c519f605-cb21-4320-b434-10%2060068-2-20-2009)

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-54	NOTE	Harmonized as EN 60068-2-54:2006 (not modified).
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58:2004 (not modified).
IEC 60068-2-69	NOTE	Harmonized as EN 60068-2-69:2007 (not modified).
IEC 61190-1-3	NOTE	Harmonized as EN 61190-1-3:2007 (not modified).

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	- ¹⁾	Environmental testing - Part 1: General and guidance	EN 60068-1	1994 ²⁾
IEC 60068-2-2	- ¹⁾	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	2007 ²⁾
IEC 60068-2-66	- ¹⁾	Environmental testing - Part 2-66: Test methods - Test Cx: Damp heat, steady state (unsaturated pressurized vapour)	EN 60068-2-66	1994 ²⁾
IEC 60068-2-78	- ¹⁾	Environmental testing - Part 2-78: Tests - Test Cb: Damp heat, steady state	EN 60068-2-78	2001 ²⁾
IEC 60194	- ¹⁾	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	2006 ²⁾
IEC 61191-3	- ¹⁾	Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies	EN 61191-3	1998 ²⁾
IEC 61191-4	- ¹⁾	Printed board assemblies - Part 4: Sectional specification - Requirements for terminal soldered assemblies	EN 61191-4	1998 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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IEC 60068-2-20

Edition 5.0 2008-07

INTERNATIONAL STANDARD

Environmental testing –
Part 2-20: Tests – Test T: Test methods for solderability and resistance to
soldering heat of devices with leads

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CONTENTS

FOREWORD.....	4
1 Scope and object.....	6
2 Normative references	6
3 Terms and definitions	7
4 Test Ta: Solderability of wire and tag terminations.....	8
4.1 Object and general description of the test.....	8
4.1.1 Test methods.....	8
4.1.2 Specimen preparation.....	8
4.1.3 Initial measurements	9
4.1.4 Accelerated ageing.....	9
4.2 Method 1: Solder bath	9
4.2.1 Description of the solder bath	9
4.2.2 Flux	10
4.2.3 Procedure.....	10
4.2.4 Test conditions	10
4.2.5 Final measurements and requirements	11
4.3 Method 2: Soldering iron at 350 °C.....	11
4.3.1 Description of soldering irons	11
4.3.2 Solder and flux	12
4.3.3 Procedure.....	12
4.3.4 Final measurements and requirements	13
4.4 Information to be given in the relevant specification	13
5 Test Tb: Resistance to soldering heat.....	13
5.1 Object and general description of the test.....	13
5.1.1 Test methods.....	13
5.1.2 Initial measurements	14
5.2 Method 1: Solder bath	14
5.2.1 Description of the solder bath	14
5.2.2 Flux	14
5.2.3 Procedure.....	14
5.2.4 Test conditions	14
5.2.5 De-wetting.....	15
5.3 Method 2: Soldering iron	15
5.3.1 Description of soldering iron	15
5.3.2 Solder and flux	15
5.3.3 Procedure.....	15
5.4 Recovery.....	16
5.5 Final measurements and requirements	16
5.6 De-wetting (if applicable).....	16
5.7 Information to be given in the relevant specification	17
Annex A (informative) Example of apparatus for accelerated steam ageing process	18
Annex B (normative) Specification for flux constituents.....	19
Bibliography.....	20
Figure 1 – Diagram of contact angle	7

Figure 2 – Position of soldering iron.....	12
Figure A.1 – Example of apparatus	18
Table 1 – Solderability, Solder bath method: Test severities (duration and temperature).....	11
Table 2 – Resistance to soldering heat, Solder bath method: Test severities (duration and temperature)	15

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENVIRONMENTAL TESTING –

**Part 2-20: Tests –
Test T: Test methods for solderability
and resistance to soldering heat of devices with leads**

FOREWORD

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International Standard IEC 60068-2-20 has been prepared by IEC technical committee 91: Electronics assembly technology.

This fifth edition cancels and replaces the fourth edition, published in 1979 and its Amendment 2 (1987). Amendment 2 includes Amendment 1. This fifth edition constitutes a technical revision and includes test conditions and requirements for use of lead-free solder.

The major technical changes with regard to the fourth edition are the following:

- the solder globule test is deleted;
- test conditions and requirements for lead-free solders are added.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/764/FDIS	91/774/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 60068 series, under the general title *Environmental testing*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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